

Taiwan Semiconductor

2A, 200V - 600V Surface Mount Super Fast Rectifier

FEATURES

TAIWAN

Glass passivated junction chip

IICONDUCTOR

- Ideal for automated placement
- Super fast recovery time for high efficiency
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- High frequency rectification
- Freewheeling application
- Switching mode converters and inverters in computer, automotive and telecommunication.

MECHANICAL DATA

- Case: DO-214AA (SMB)
- Molding compound meets UL 94 V-0 flammability rating
- Moisture sensitivity level: level 1, per J-STD-020
- Packing code with suffix "G" means green compound (halogen-free)
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 1A whisker test
- Polarity: As marked
- Weight: 0.09 g (approximately)

| KEY PARAMETERS | | | | |
|--------------------|----------------------|----|--|--|
| PARAMETER | PARAMETER VALUE UNIT | | | |
| I _{F(AV)} | 2 | А | | |
| V _{RRM} | 200 - 600 | V | | |
| I _{FSM} | 50 | А | | |
| T _{J MAX} | 150 | °C | | |
| Package | DO-214AA (SMB) | | | |
| Configuration | Single dice | | | |





DO-214AA (SMB)

| ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted) | | | | | | |
|---|--------------------|-----------------|--------|--------|------|--|
| PARAMETER | SYMBOL | ES2D-T | ES2G-T | ES2J-T | UNIT | |
| Marking code on the device | | ES2D | ES2G | ES2J | | |
| Repetitive peak reverse voltage | V _{RRM} | 200 | 400 | 600 | V | |
| Reverse voltage, total rms value | V _{RMS} | 140 | 280 | 420 | V | |
| Maximum DC blocking voltage | V _{DC} | 200 | 400 | 600 | V | |
| Forward current | I _{F(AV)} | 2 | | А | | |
| Surge peak forward current, 8.3 ms single half sine- wave superimposed on rated load per diode | I _{FSM} | 50 4 | | А | | |
| Junction temperature | TJ | - 55 to +150 ° | | °C | | |
| Storage temperature | T _{STG} | - 55 to +150 °C | | | °C | |





| THERMAL PERFORMANCE | | | | | |
|--|------------------|-----|------|--|--|
| PARAMETER | SYMBOL | ТҮР | UNIT | | |
| Junction-to-lead thermal resistance | $R_{\Theta JL}$ | 20 | °C/W | | |
| Junction-to-ambient thermal resistance | R _{eja} | 75 | °C/W | | |

| ELECTRICAL SPECIFICATIONS (T _A = 25°C unless otherwise noted) | | | | | | |
|--|--------|---|------------------|-----|------|------|
| PARAMETER | | CONDITIONS | SYMBOL | ТҮР | MAX | UNIT |
| | ES2D-T | I _F = 1A, T _J = 25°C | | - | 0.95 | V |
| Forward voltage per diode (1) | ES2G-T | | V _F | - | 1.30 | V |
| | ES2J-T | | | - | 1.70 | V |
| Reverse current @ rated V _R per diode ⁽²⁾ | | $T_J = 25^{\circ}C$ | - I _R | - | 10 | μA |
| | | T _J = 125°C | | - | 350 | μA |
| ES2D-T | | | | 25 | - | pF |
| Junction capacitance | ES2G-T | 1 MHz, V _R =4V | CJ | | | pF |
| | ES2J-T | | | 20 | - | pF |
| Reverse recovery time | | I _F =0.5A , I _R =1.0A I _{RR} =0.25A | t _{rr} | - | 35 | nS |

Notes:

1. Pulse test with PW=0.3 ms

2. Pulse test with PW=30 ms

ORDERING INFORMATION

| PART NO. | PACKING CODE | PACKING CODE SUFFIX | PACKAGE | PACKING | |
|----------|--------------|------------------------|---------|--------------------------|--|
| | R5 | | SMB | 850 / 7" Plastic reel | |
| ES2x-T | R4 | G | SMB | 3,000 / 13" Paper reel | |
| (Note 1) | M4 | | SMB | 3,000 / 13" Plastic reel | |

Note:

1. "x" defines voltage from 200V (ES2D-T) to 600V (ES2J-T)

2. Whole series with green compound

| EXAMPLE | | | | |
|-------------|----------|--------------|------------------------|----------------|
| EXAMPLE P/N | PART NO. | PACKING CODE | PACKING CODE SUFFIX | DESCRIPTION |
| ES2J-T R5G | ES2J-T | R5 | G | Green compound |



CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

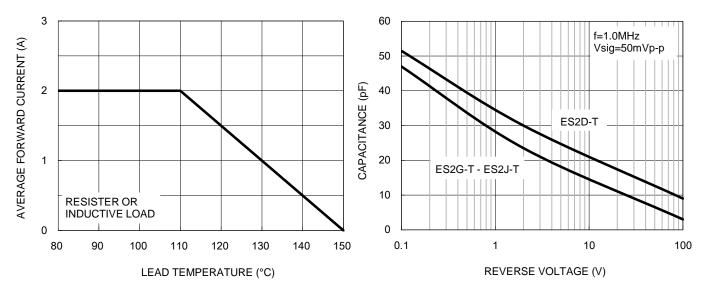
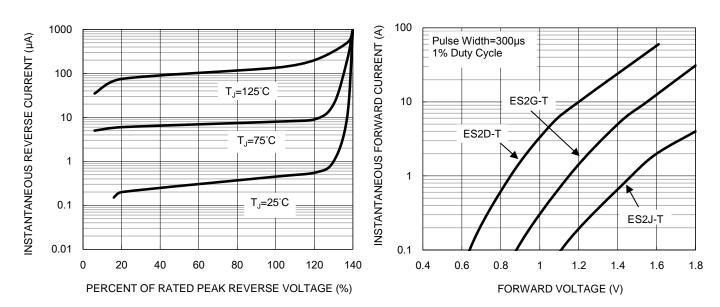


Fig1. Forward Current Derating Curve

Fig3. Typical Reverse Characteristics

Fig4. Typical Forward Characteristics

Fig2. Typical Junction Capacitance



Version:C1910



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Fig5. Maximum Non-repetitive Forward Surge Current

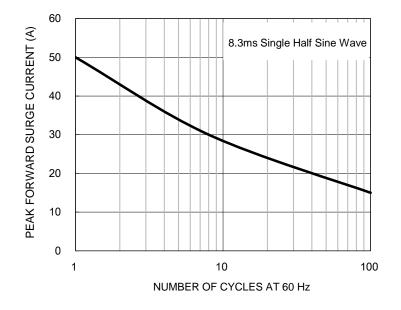
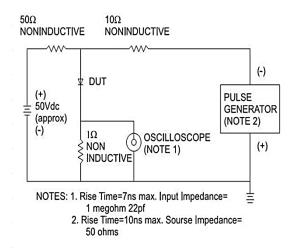
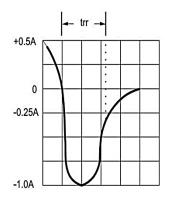


Fig6. Reverse Recovery Time Characteristic And Test Circuit Diagram

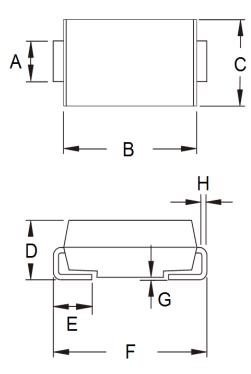






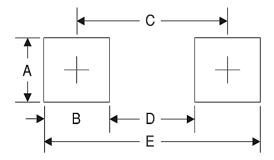
PACKAGE OUTLINE DIMENSIONS

DO-214AA (SMB)



| DIM. | Unit (mm) | | Unit (inch) | |
|--------|-----------|------|-------------|-------|
| Dilvi. | Min | Max | Min | Max |
| А | 1.95 | 2.10 | 0.077 | 0.083 |
| В | 4.25 | 4.75 | 0.167 | 0.187 |
| С | 3.48 | 3.73 | 0.137 | 0.147 |
| D | 1.99 | 2.61 | 0.078 | 0.103 |
| Е | 0.90 | 1.41 | 0.035 | 0.056 |
| F | 5.10 | 5.46 | 0.201 | 0.209 |
| G | 0.05 | 0.20 | 0.004 | 0.008 |
| Н | 0.15 | 0.31 | 0.006 | 0.012 |

SUGGESTED PAD LAYOUT



| Symbol | Unit (mm) | Unit (inch) |
|--------|-----------|-------------|
| A | 2.3 | 0.091 |
| В | 2.5 | 0.098 |
| С | 4.3 | 0.169 |
| D | 1.8 | 0.071 |
| E | 6.8 | 0.268 |

MARKING DIAGRAM



P/N = Marking Code

= Green Compound G

YW = Date Code

F = Factory Code



ES2D-T - ES2J-T

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